

INTERNATIONAL STANDARD

NORME INTERNATIONALE

Printed board design, manufacture and assembly – Terms and definitions

Conception, fabrication et assemblage des cartes imprimées – Termes et définitions

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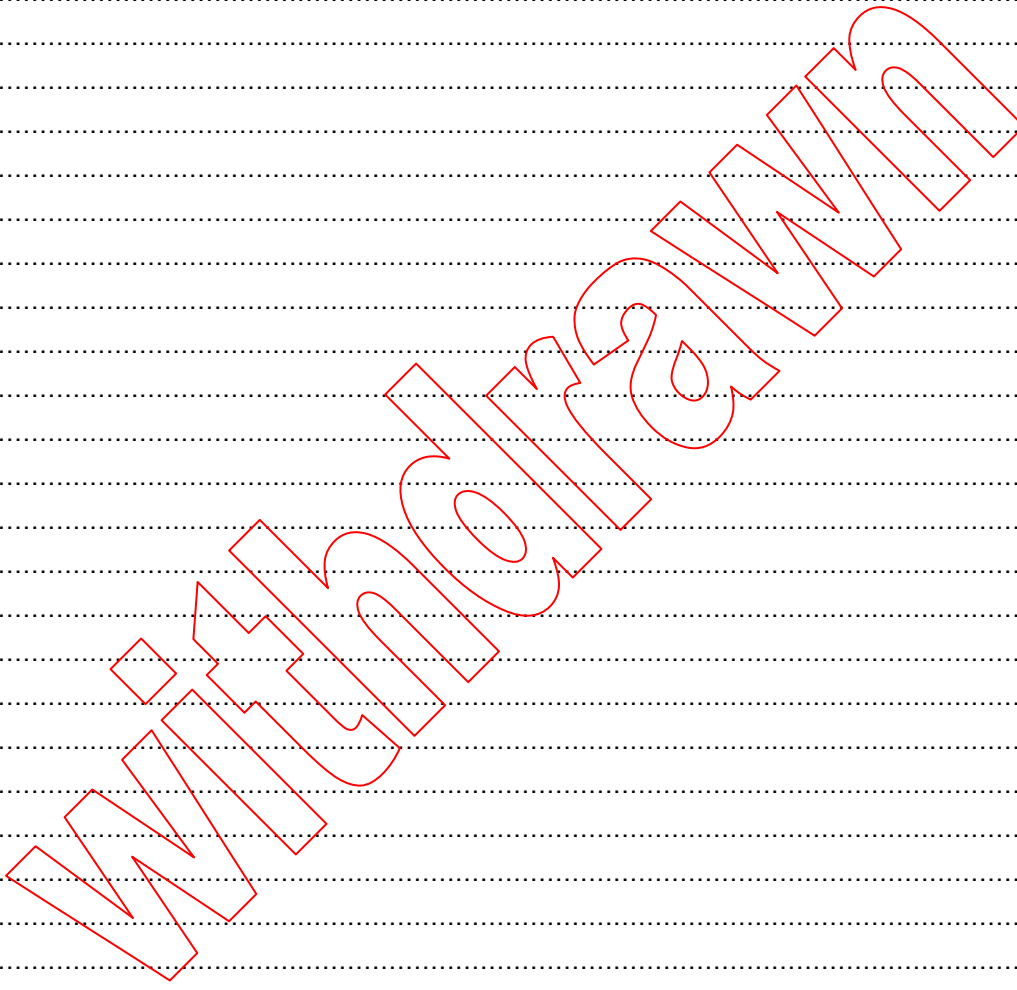
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CONTENTS

FOREWORD.....	6
INTRODUCTION.....	8
1 Scope.....	9
2 Normative references	9
3 Terms and definitions	9
4 A.....	9
5 B.....	23
6 C.....	41
7 D.....	71
8 E.....	83
9 F.....	93
10 G.....	106
11 H.....	109
12 I.....	117
13 J.....	122
14 K.....	123
15 L.....	125
16 M.....	134
17 N.....	145
18 O.....	149
19 P.....	154
20 Q.....	175
21 R.....	176
22 S.....	188
23 T.....	213
24 U.....	225
25 V.....	228
26 W.....	232
27 X.....	237
28 Y.....	237
29 Z.....	238
Annex A (informative) Principles and use of the classification code	239
A.1 General.....	239
A.2 Background.....	239
A.3 List of codes	240
Annex B (informative) Abbreviations	243
B.1 – A –.....	243
B.2 – B –.....	243
B.3 – C –.....	244
B.4 – D –.....	246
B.5 – E –.....	247
B.6 – F –.....	248



B.7	– G –	248
B.8	– H –	248
B.9	– I –	249
B.10	– J –	249
B.11	– K –	249
B.12	– L –	249
B.13	– M –	250
B.14	– N –	251
B.15	– O –	252
B.16	– P –	252
B.17	– Q –	253
B.18	– R –	253
B.19	– S –	254
B.20	– T –	255
B.21	– U –	256
B.22	– V –	256
B.23	– W –	256
B.24	– Z –	256
Bibliography		257
Figure 1	– Access hole	11
Figure 2	– Alignment mark	14
Figure 3	– Lands with anchoring spurs	17
Figure 4	– Annular ring (annular width)	18
Figure 5	– Area array	19
Figure 6	– Simplified flow chart of printed board design/fabrication sequence	20
Figure 7	– Aspect ratio (hole)	21
Figure 8	– Asymmetric stripline	22
Figure 9	– Axial lead	23
Figure 10	– Back bonding	24
Figure 11	– Back-bared land	24
Figure 12	– Ball grid array (BGA)	26
Figure 13	– Barrel crack	27
Figure 14	– Example of feature location using baseline dimensions	28
Figure 15	– Bathtub curve	29
Figure 16	– Beam-lead device	30
Figure 17	– Bifurcated solder terminal	31
Figure 18	– Buried via and blind via	33
Figure 19	– Bow	36
Figure 20	– Breakaway	37
Figure 21	– Bumped die	39
Figure 22	– But plating joint (wrap plating)	41
Figure 23	– Button plating	41
Figure 24	– Castellated	44
Figure 25	– Centre to centre spacing (pitch)	44

Figure 26 – Typical characteristic curve	46
Figure 27 – Chip on board (COB).....	49
Figure 28 – Clearance hole	51
Figure 29 – Clinched-wire through connection.....	51
Figure 30 – Comb pattern	53
Figure 31 – Conductor base spacing	58
Figure 32 – Conductor spacing	59
Figure 33 – Contact angle (soldering)	61
Figure 34 – Crosshatching	68
Figure 35 – Cup solder terminal	69
Figure 36 – Dewetting	76
Figure 37 – Example of an embedded component.....	87
Figure 38 – Embedded passive component (device)	88
Figure 39 – Etch factor	90
Figure 40 – Etchback	90
Figure 41 – Etching indicator	91
Figure 42 – Fillet (adhesive)	96
Figure 43 – Flag	99
Figure 44 – Flare	100
Figure 45 – Flip chip	102
Figure 46 – Ground plane clearance	109
Figure 47 – Heel fillet.....	111
Figure 48 – Histogram	112
Figure 49 – Hole knee.....	113
Figure 50 – Hole breakout.....	113
Figure 51 – Hole void.....	114
Figure 52 – Hook	115
Figure 53 – Hook solder terminal	115
Figure 54 – Layer-to-layer spacing.....	128
Figure 55 – Leaded surface-mount component – Gull wing shaped lead	129
Figure 56 – Magnification power parameters.....	135
Figure 57 – Meniscus.....	137
Figure 58 – Microstrip	139
Figure 59 – Mirrored pattern	141
Figure 60 – Nail heading.....	145
Figure 61 – Negative etchback.....	145
Figure 62 – Nonfunctional interfacial connection	147
Figure 63 – Nonwetting	148
Figure 64 – Normal distribution	148
Figure 65 – Open point	151
Figure 66 – Outgrowth, overhang and undercut.....	152
Figure 67 – Outgrowth, overhang and undercut.....	153
Figure 68 – Overlap (drill).....	153

Figure 69 – Passive array	157
Figure 70 – Perforated (pierced) solder terminal	159
Figure 71 – Pin grid array	162
Figure 72 – Plated through-hole (PTH).....	164
Figure 73 – Primary flare	170
Figure 74 – Primary taper	170
Figure 75 – Resin recession	181
Figure 76 – Printed board viewing orientations.....	185
Figure 77 – Shadowing	192
Figure 78 – Tape automated bonding.....	214
Figure 79 – Tombstoned component	221
Figure 80 – Turret solder terminal.....	225
Figure 81 – Via planarization	230
Figure 82 – Wrap plating.....	237

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**PRINTED BOARD DESIGN, MANUFACTURE AND ASSEMBLY –
TERMS AND DEFINITIONS**

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International Standard IEC 60194 has been prepared by subcommittee 91: Electronics assembly technology.

This sixth edition cancels and replaces the fifth edition, published in 2006 and constitutes a technical revision.

The main changes with respect to the previous edition are the following: Some two hundred terms and definitions have been updated, where applicable, and another two hundred new terms and definitions have been added.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/1236/FDIS	91/1253/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

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INTRODUCTION

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